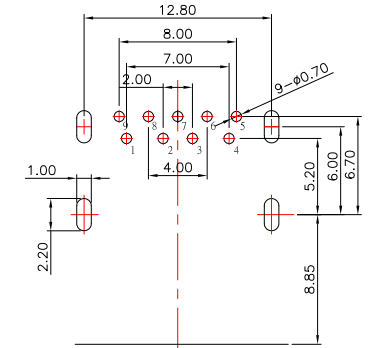
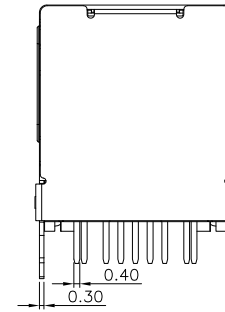
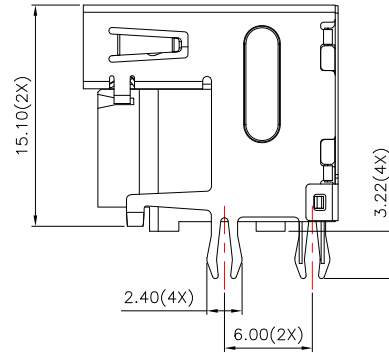
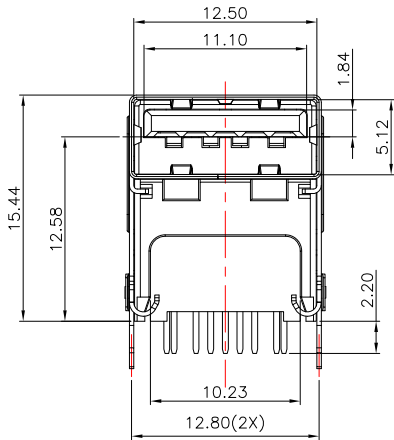


USB 3.0 AF 架高型的下方空間是擺放Type C connector,
先打件Type C connector,再打件USB 3.0 AF



RECOMMENDED PCB LAYOUT



NOTE:

1.MATERIAL:

- 1.1 Housing: PA66
- 1.2 Contact: PHOSPHOR BRONZE
- 1.3 Shell: SUS

2.Finish:

- 2.1 Contact: Plated Gold in Mating Area ;
Tin Plated on Solder Balls ;
Nickel under plated overall
- 2.2 Shell: Nickel under Plated surface layer

3.SPECIFICATION:

- 3.1 Current Rate: 1.8 A
- 3.2 insulator Resistance:100MΩ Min
- 3.3 Dielectric Strength: 500V AC
- 3.4 Contact Resistance: 30mΩ Max
- 3.5 Operation Temperature: -40°C ~ +85°C
- 3.6 Insertion Force: 35 N
- 3.7 Extraction Force: 10 N

SUA-110H13-30xx-S277

鍍層厚度: COLOR :

Blank : 1u"
2 : 15u"
3 : 30u"

BLUE : Blank
Black : B
Red : R

Contact Number	Signal Name
PIN1	VBUS
PIN2	D-
PIN3	D+
PIN4	GND
PIN5	StdA_SSRX-
PIN6	StdA_SSRX+
PIN7	GND_DRAIN
PIN8	StdA_SSTX-
PIN9	StdA_SSTX+
Shell	Shield

CONTACT 建倚科技股份有限公司
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED :
Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3

3RD. ANGEL'S

UNITS MM

DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	11/26/21			
CHECKED BY:	DATE	FINISH	MODLE	USB AF DIP 架高 CH=12.58mm
Jacky Chen	11/26/21			
APPROVED BY:	DATE	SCALE	DWG NO.	SUA-110H13-30xx-S277
Tony Kao	11/26/21	1 : 1	PART NO.	SUA-110H13-30xx-S277
		SHEET NO.	1 of 1	
				SIZE A4
				VER R1

1	新增產品說明和更新材質	Jack	112621
ITEM NO.	DESCRIPTION	DRAWN	DATE